

07-05-2006



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Attorney Docket No. 09700.0180-00  
SAP Reference No. 2006P00706US

To the Director of the U.S. Patent  
Please record the attached original documents or copy thereof.

103269065

Mail Stop Assignment Recordation Services

1. Name of conveying party(ies):  
(1) Frank BRUNSWIG, (2) Pragnesh B. MISTRY, (3) Prashanth RAI, and (4) Abhay A. TIPLE

2. Name and address of receiving party(ies):

Name: SAP AG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Internal Address:

3. Nature of conveyance:

Street Address: Dietmar-Hopp-Allee 16

☒ Assignment

☐ Merger

City: Walldorf

☐ Security Agreement

☐ Change of Name

Country: Germany Postal Code: D-69190

☐ Joint Research Agreement

☐ Government Interest Assignment

Additional name(s) & Address(es) attached?

☐ Executive Order 9494, Confirmatory License

☐ Other:

☐ Yes

☒ No

Execution Date: (1) June 14, 2006, (2) June 20, 2006, (3) June 1, 2006, and (4) June 12, 2006

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application: (1) June 14, 2006, (2) June 20, 2006, (3) June 1, 2006, and (4) June 12, 2006

A. Patent Application Number(s):

B. Patent Number(s):

Additional numbers attached?

☐ Yes

☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

6. Total number of applications and patents involved: 1

Name: Leila R. Abdi

7. Total fee (37 CFR 1.21(h) and 3.41): \$40

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

☒ Enclosed (Please charge deficiency or credit overpayment to deposit account 06-0916)

Street Address: 901 New York Avenue, N.W.

☐ Authorized to be charged to deposit account

City: Washington, D.C.

State: Zip: 20001-4413

8. Deposit Account No.: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Signed:

*Leila R. Abdi*

Leila R. Abdi

June 27, 2006

Date

Total number of pages including cover sheet, attachments and documents: 8

5/2006

06/29/2006 JBALINAN 00000057 11475059

04 FC:8021

40.00 0P

PATENT  
REEL: 018037 FRAME: 0513

## ASSIGNMENT

WHEREAS WE, the below named inventors [hereinafter referred to as Assignors], have made an invention entitled:

### SYSTEMS AND METHODS FOR PROVIDING A MOCKUP DATA GENERATOR

for which We filed an application for United States Letters Patent on concurrently herewith; and

WHEREAS, SAP AG, a corporation of India whose post office address is Dietmar-Hopp-Allee 16, D-69190, Walldorf, Germany [hereinafter referred to as Assignee], is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, We, as Assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention, and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that We have the full right to convey the interest assigned by this Assignment, and We have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, WE have hereunto set our hands.

Name: Frank BRUNSWIG

WITNESSED BY,

Address: Oberer Rainweg 18  
69118 Heidelberg, Germany

Name:  
(Printed)

BINDEWALD

Signature:

Frank Brunswig

Signature:

B. Bindewald

Date:

14.06.2006

Date:

14.6.2006

Name: Pragnesh B. MISTRY  
Address: T-3, Jan Jeeve Enclave, Thima Redday  
Layout, C.V. Raman Nagar, Bangalore -  
560093, India  
Signature: \_\_\_\_\_  
Date: \_\_\_\_\_

WITNESSED BY,

Name: \_\_\_\_\_  
(Printed)  
Signature: \_\_\_\_\_  
Date: \_\_\_\_\_

Name: Prashanth RAI  
Address: 91/2, 2nd Main, 3rd Cross, Opp  
Aryavartha, Vivekanada Layout,  
Banshankri, Bangalore-78, India  
Signature: \_\_\_\_\_  
Date: \_\_\_\_\_

WITNESSED BY,

Name: \_\_\_\_\_  
(Printed)  
Signature: \_\_\_\_\_  
Date: \_\_\_\_\_

Name: Abhay A. TIPLE  
Address: Freiherr-vom-stein-str. 39  
Sandhausen 69207 Germany  
Signature: \_\_\_\_\_  
Date: \_\_\_\_\_

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Name: \_\_\_\_\_  
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Name: \_\_\_\_\_  
(Printed)

Signature: \_\_\_\_\_

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Date: \_\_\_\_\_

Name: Pragnesh B. MISTRY

Address: 407/43, Sardar Patel Society,  
Oppo:- Shri Gattu Vidyalaya,  
Near: Bhavi Bunglow,  
GIDC Estate,  
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Gujarat, INDIA.

Signature: Pallistry

Date: 20/06/2006

Name: Prashanth RAI

Address: 91/2, 2nd Main, 3rd Cross, Opp  
Aryavatha, Vivekanada Layout,  
Banshankri, Bangalore-78, India

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Name: Abhay A. TIPLE

Address: Freiherr-vom-stein-str. 39  
Sandhausen 69207 Germany

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

WITNESSED BY, MANOJ GUPTA

Name: \_\_\_\_\_  
(Printed)

Signature: Manoj Gupta

Date: 20/06/2006

WITNESSED BY,

Name: \_\_\_\_\_  
(Printed)

Signature: \_\_\_\_\_

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Date: \_\_\_\_\_

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Layout, C.V. Raman Nagar, Bangalore -  
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Name: Prashanth RAI  
Address: 91/2, 2nd Main, 3rd Cross, Opp  
Aryavartha, Vivekanada Layout,  
Banshankri, Bangalore-78, India  
Signature:   
Date: 01/06/2006

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Name: Pramod S.J  
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Signature:   
Date: 01 June, 2006

Name: Abhay A. TIPLE  
Address: Freiherr-vom-stein-str. 39  
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Signature: \_\_\_\_\_  
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Date: \_\_\_\_\_


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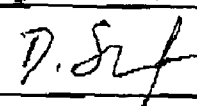
Name: Prashanth RAI  
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Date: \_\_\_\_\_

Name: Abhay A. TIPLE  
Address: Freiherr-vom-stein-str. 39  
Sandhausen 69207 Germany  
Signature:   
Date: 12 JUN-06

WITNESSED BY,

Name: DIRK STUMPF  
(Printed)  
Signature:   
Date: 12-JUN-06